

Specification Amendments

Please amend the text of the specification on page 15, line 8 to page 16, line 10 as follows:

-- In the formation of the reaction mixture, an alkylalkoxysilane may be incorporated as a modifier (F), for example, in an amount of from 0.02 to 0.2 mol per mol of the silicon compound (A), as the case requires, in addition to the silicon compounds (A), (B) and (C), the alcohol (D) and the oxalic acid (E). Preferred examples of the modifier (F) include trialkoxysilanes such as methyltrimethoxysilane, methyltriethoxysilane, ethyltrimethoxysilane, ethyltriethoxysilane, propyltrimethoxysilane, propyltriethoxysilane, butyltrimethoxysilane, butyltriethoxysilane, pentyltrimethoxysilane, pentyltriethoxysilane, heptyltrimethoxysilane, heptyltriethoxysilane, octyltrimethoxysilane, octyltriethoxysilane, dodecyltrimethoxysilane, dodecyltriethoxysilane, hexadecyltrimethoxysilane, hexadecyltriethoxysilane, octadecyltrimethoxysilane, octadecyltriethoxysilane, phenyltrimethoxysilane, phenyltriethoxysilane, vinyltrimethoxysilane, vinyltriethoxysilane, γ -aminopropyltrimethoxysilane, γ -aminopropyltriethoxysilane, γ -glycidoxypropyltrimethoxysilane, γ -glycidoxypropyltriethoxysilane, γ -methacryloxypropyltrimethoxysilane and γ -methacryloxypropyltriethoxysilane, and dialkoxysilanes such as dimethyldimethoxysilane, dimethyldiethoxysilane, γ -ureidopropylmethyldimethoxysilane and γ -ureidopropylmethyldiethoxysilane. These modifiers may be used alone or in combination as a mixture of two or more of them. --

Please amend the text of the specification on page 29, lines 6-13 as follows:

-- A hard coat-covered TAC film manufactured by Nippon Paper Industries Co., Ltd. was immersed in a 5 wt% potassium hydroxide (KOH) aqueous solution heated to 40°C for 3 minutes for alkali treatment, then washed with water and then immersed in a 0.5 wt% sulfuric

acid (H_2SO_4) aqueous solution at room temperature for 30 ~~minute~~ seconds for neutralization,
followed by washing with water and drying. --